

METHOD AND STRUCTURE FOR
DETERMINING THERMAL CYCLE RELIABILITY

ABSTRACT OF THE DISCLOSURE

5 A device and method for evaluating reliability of a
semiconductor chip structure built by a manufacturing
process includes a test structure built in accordance with
a manufacturing process. The test structure is thermal
cycled and the yield of the test structure is measured.
10 The reliability of the semiconductor chip structure built
by the manufacturing process is evaluated based on the
yield performance before the thermal cycling.